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**PATENT**  
Attorney Docket No.: 02307V-121600US  
Client Ref. No.: B02-027-1

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

On March 9, 2004

TOWNSEND and TOWNSEND and CREW LLP

By: Mark D. Dees

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

William R. ASHURST et al.

Application No.: 10/086,652

Filed: February 28, 2002

For: VAPOR DEPOSITION OF  
DIHALODIALKYLSILANES

Customer No.: 20350

Confirmation No. 6884

Examiner: Markham, Wesley D.

Technology Center/Art Unit: 1762

### DECLARATION OF WILLIAM R. ASHURST UNDER 37 CFR §1.131

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

I, WILLIAM R. ASHURST, hereby declare as follows:

1. I am the William R. Ashurst listed as the first-named inventor in the above-identified patent application. I have reviewed the document submitted herewith bearing the caption "AMENDMENT NO. 1" including the amendment to the claims of the application.
  
2. Attached hereto as Exhibits A and B are true copies, except that dates have been blocked out, of pages from a laboratory notebook or notebooks maintained by me, the entries on these pages having been made by me. The drawing and entries on Exhibit A are notes

taken during a conference between myself and one of my coinventors on this patent application, and the entries on Exhibit B are accurate descriptions of materials and processing conditions that I used. The drawing on Exhibit A and the entries on both Exhibits describe coating procedures and materials that fall within the scope of claim 1 of the patent application. Both notebook pages were completed prior to May 7, 2001.

3. I further declare that the above statements were made with the knowledge that willful false statements and the like are punishable by fine or imprisonment or both, under Section 1001 of Title 18 of the United States Code, and that any such willful false statement may jeopardize the validity of the subject patent application or any patent resulting therefrom.

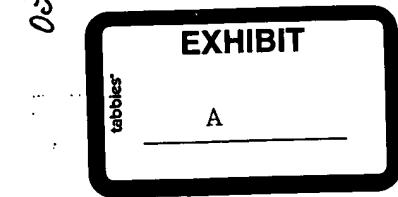
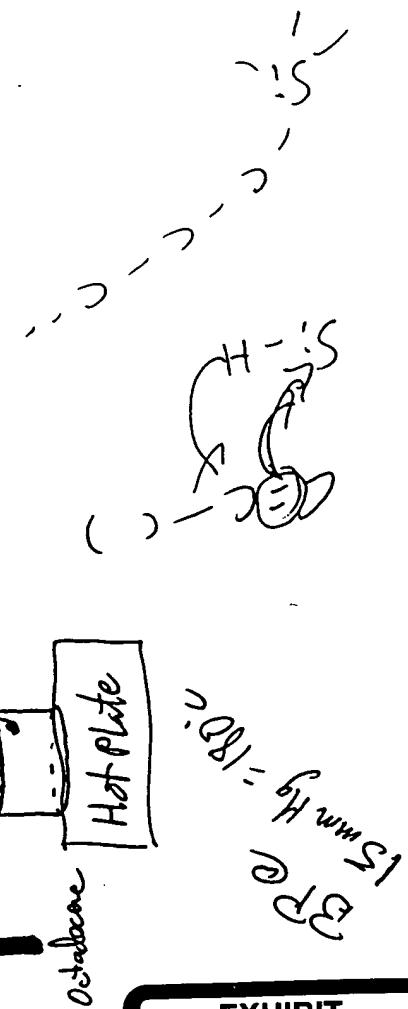
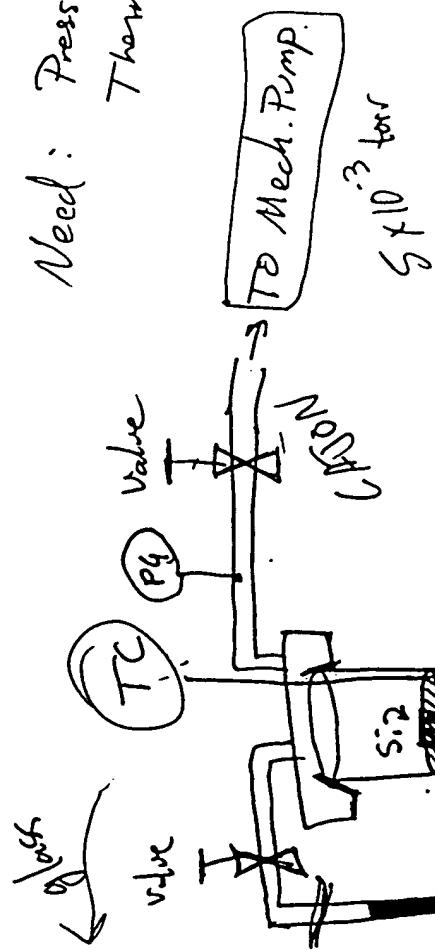
Date: 03/04/2004 By: William R. Ashurst  
William R. Ashurst

Attachments: Exhibits A and B

MHH:mhh  
60156498 v1

Meeting w/ Will Freg of Bosch

Need: Pressure Gauge  
Thermocouple Feed-thru.



Vap SAM coater

Processing WRA0067 + WRA0068

Sandia Reticle 156

Standard Release:

90 nm HF/MCl

Water Rinse

H<sub>2</sub>O<sub>2</sub> xfer

Degum @ 70°C 10 min

H<sub>2</sub>O<sub>2</sub> @ 80°C 10 min

Water Rinse + Dry

Chiplet + WRA0068 >> VapSAM(DDMS)

Chiplet + WRA0068 put in Vapsam

Pumpdown < 1x10<sup>-4</sup>

heat up ~ 35°C

expose 2 torr H<sub>2</sub>O + 1 torr DDMS for 5 min

pumpdown < 1x10<sup>-4</sup>

T = 43°C

expose ~~2.2~~ 2.2 torr H<sub>2</sub>O + 1.1 torr DDMS for 20 min

pumpdown < 1x10<sup>-4</sup>

N<sub>2</sub> back fill

remove water & chiplet = 100°

EXHIBIT

B